MMBTA56LT1 is a Preferred Device

# **Driver Transistors**

# **PNP Silicon**

#### **Features**

• Pb-Free Package is Available

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector – Emitter Voltage  MMBTA  MMBTA		-60 -80	Vdc
Collector-Base Voltage  MMBTA  MMBTA		-60 -80	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-4.0	Vdc
Collector Current – Continuous	I <sub>C</sub>	-500	mAdc

### THERMAL CHARACTERISTICS

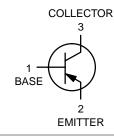
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

- 1. FR-5 =  $1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina =  $0.4 \times 0.3 \times 0.024$  in. 99.5% alumina.



## ON Semiconductor®

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SOT-23 CASE 318 STYLE 6

## **MARKING DIAGRAMS**





MMBTA55LT1

MMBTA56LT1

2H, 2GM = Specific Device Code X = Date Code

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBTA55LT1	SOT-23	3000/Tape & Reel
MMBTA55LT3	SOT-23	10,000/Tape & Reel
MMBTA56LT1	SOT-23	3000/Tape & Reel
MMBTA56LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel
MMBTA56LT3	SOT-23	10,000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

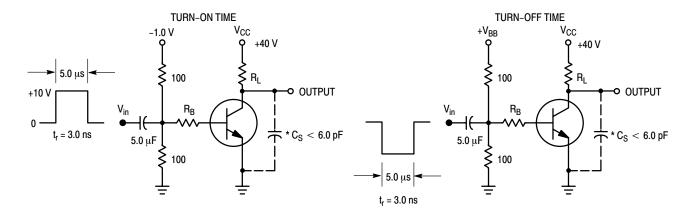
**Preferred** devices are recommended choices for future use and best overall value.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS			•	•	
Collector – Emitter Breakdown Voltage (Note 3) $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	MMBTA55 MMBTA56	V <sub>(BR)CEO</sub>	-60 -80	- -	Vdc
Emitter – Base Breakdown Voltage $(I_E = -100 \mu Adc, I_C = 0)$		V <sub>(BR)EBO</sub>	-4.0	_	Vdc
Collector Cutoff Current (V <sub>CE</sub> = -60 Vdc, I <sub>B</sub> = 0)		I <sub>CES</sub>	-	-0.1	μAdc
Collector Cutoff Current $(V_{CB} = -60 \text{ Vdc}, I_E = 0)$ $(V_{CB} = -80 \text{ Vdc}, I_E = 0)$	MMBTA55 MMBTA56	I <sub>CBO</sub>	- -	-0.1 -0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain $ (I_C = -10 \text{ mAdc}, V_{CE} = -1.0 \text{ Vdc}) $ $ (I_C = -100 \text{ mAdc}, V_{CE} = -1.0 \text{ Vdc}) $		h <sub>FE</sub>	100 100	- -	-
Collector – Emitter Saturation Voltage $(I_C = -100 \text{ mAdc}, I_B = -10 \text{ mAdc})$		V <sub>CE(sat)</sub>	-	-0.25	Vdc
Base-Emitter On Voltage (I <sub>C</sub> = -100 mAdc, V <sub>CE</sub> = -1.0 Vdc)		V <sub>BE(on)</sub>	-	-1.2	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product (Note 4) (I <sub>C</sub> = –100 mAdc, V <sub>CE</sub> = –1.0 Vdc, f = 100 MHz)		f⊤	50	_	MHz

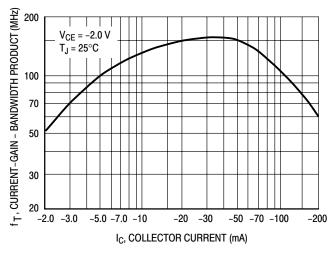
<sup>3.</sup> Pulse Test: Pulse Width  $\leq 300 \,\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

<sup>4.</sup> f<sub>T</sub> is defined as the frequency at which |h<sub>fe</sub>| extrapolates to unity.



<sup>\*</sup>Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

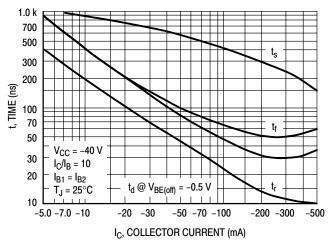
Figure 1. Switching Time Test Circuits



100 70 C<sub>ibo</sub> 50 C, CAPACITANCE (pF) 30 20 10 7.0 -0.1 -0.2 -1.0 -2.0 -5.0 -10 -20 -50 -100 V<sub>R</sub>, REVERSE VOLTAGE (VOLTS)

Figure 2. Current-Gain — Bandwidth Product

Figure 3. Capacitance



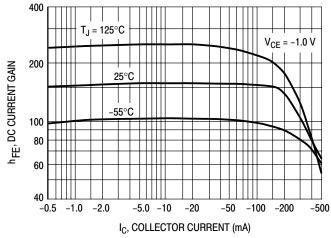


Figure 4. Switching Time

Figure 5. DC Current Gain

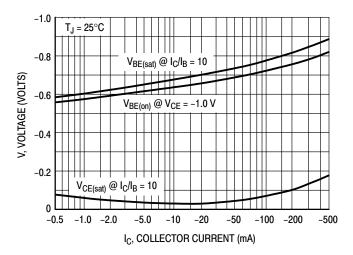
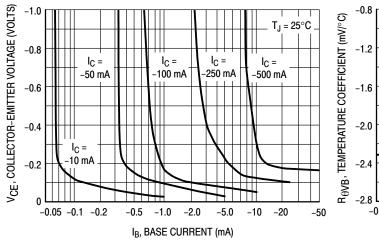


Figure 6. "ON" Voltages



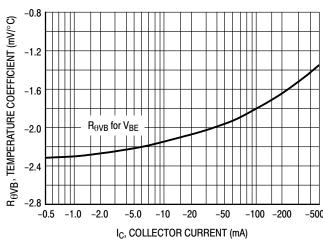
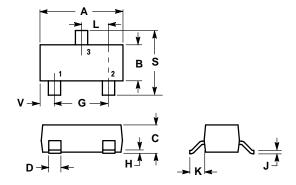


Figure 7. Collector Saturation Region

Figure 8. Base–Emitter Temperature Coefficient

# **PACKAGE DIMENSIONS**

## SOT-23 (TO-236) CASE 318-08 **ISSUE AH**



#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: INCH.

  3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL

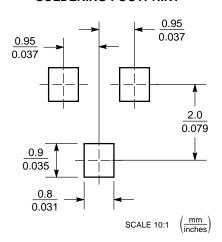
  4. 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60

STYLE 6: PIN 1. BASE

- 2. EMITTER
- 3. COLLECTOR

## **SOLDERING FOOTPRINT\***



## SOT-23

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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